

## Chip Attenuator 0302, 0404

Type: **EXB 14AT, 24AT**



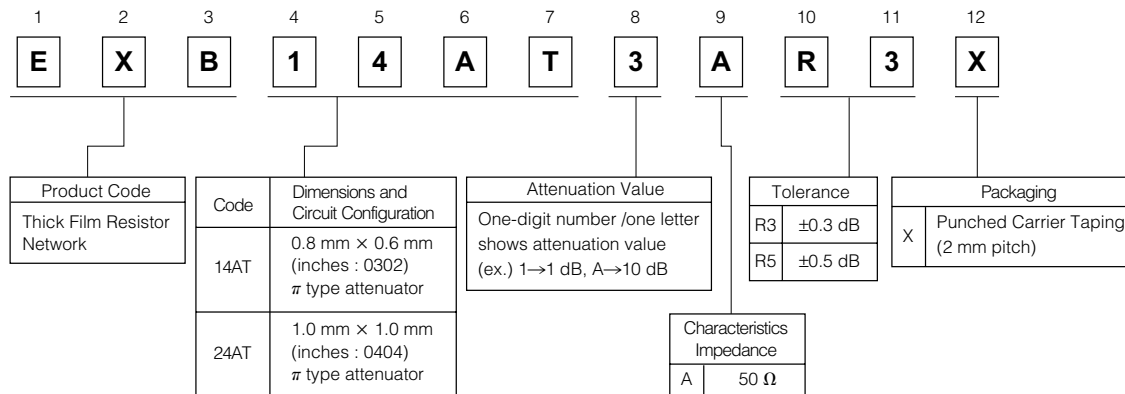
### ■ Features

- Unbalanced  $\pi$  type attenuator circuit in one chip  
EXB14AT(0.8 mm × 0.6 mm), EXB24AT(1.0 mm × 1.0 mm)
- Reduced mounting area :  
EXB14AT : About 60% smaller than the area of an attenuator circuit consisting of three 0603 chip resistors, almost equal to the area of three 0402 chip resistors  
EXB24AT : About 50% smaller than the area of an attenuator circuit consisting of three 1005 chip resistors, almost equal to the area of three 0603 chip resistors
- Mounting cost reduction : (Only 1 chip placed as compared to 3)
- Attenuation : 1 dB to 10 dB

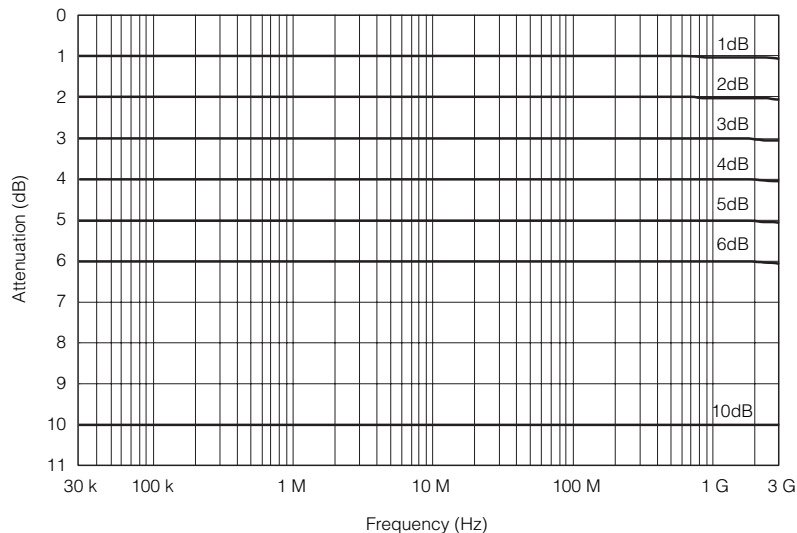
### ■ Recommended Applications

- Attenuation / level control / impedance matching of high frequency (communication signalling equipment cellular phones(GSM, CDMA, PDC, etc.), PHS, PDAs)

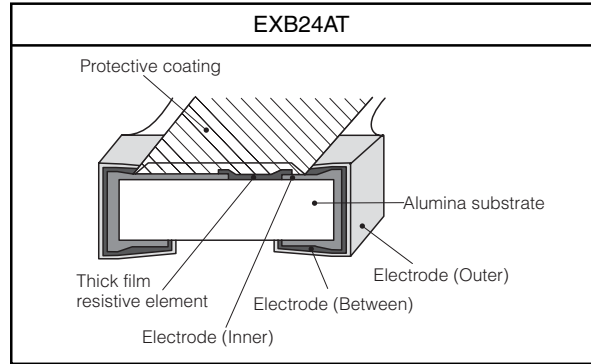
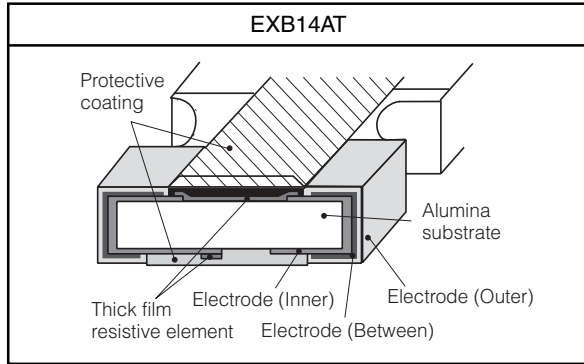
### ■ Explanation of Part Numbers



### ■ Attenuation-Frequency Characteristics (EXB14AT, EXB24AT)



## Construction



## Dimensions (not to scale)

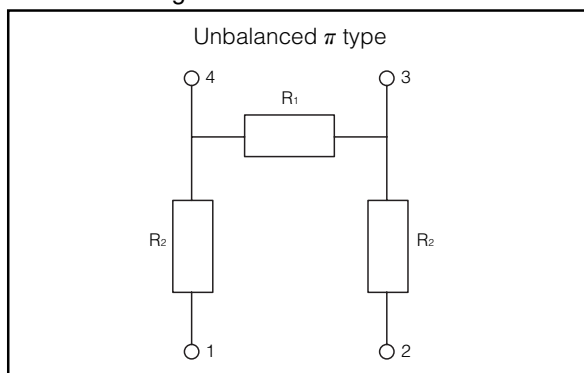
Dimensions (mm)	L	W	T	A	B
	0.80 <sup>+0.10</sup>	0.60 <sup>+0.10</sup>	0.35 <sup>+0.10</sup>	0.35 <sup>+0.10</sup>	0.15 <sup>+0.10</sup>
Dimensions (mm)	C	P (typical value)			
	0.15 <sup>+0.10</sup>	0.50			

<Marking Configuration>  
 The bar marking for recognizing terminal direction is located on the side of terminal 3, 4.  
 Mass (Weight) [1000 pcs.] : 0.7 g

Dimensions (mm)	L	W	T	A	B
	1.00 <sup>+0.10</sup>	1.00 <sup>+0.10</sup>	0.35 <sup>+0.10</sup>	0.40 <sup>+0.10</sup>	0.15 <sup>+0.10</sup>
Dimensions (mm)	C	P (typical value)			
	0.25 <sup>+0.10</sup>	0.65			

<Marking Configuration>  
 The bar marking for recognizing terminal direction is located on the side of terminal 4.  
 Mass (Weight) [1000 pcs.] : 1.1 g

## Circuit Configuration



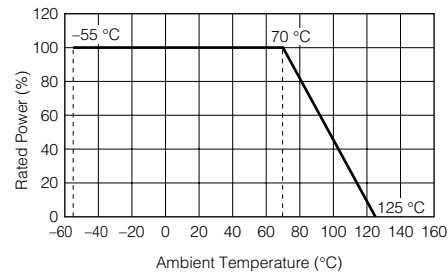
## ■ Ratings

Type	EXB14AT, EXB24AT
Attenuation Value	1 dB, 2 dB, 3 dB, 4 dB, 5 dB, 6 dB, 10 dB*
Attenuation Value Tolerance	1 dB, 2 dB, 3 dB, 4 dB, 5 dB : ±0.3 dB 6 dB, 10 dB : ±0.5 dB
Characteristic Impedance	50 Ω
Power Rating	0.04 W /package
Frequency Range	DC to 3.0 GHz
VSWR (Voltage Standing Wave Ratio)	1.3 max.
Number of Resistors	3 resistors
Number of Terminals	4 terminals
Category Temperature Range (Operating Temperature Range)	-55 °C to +125 °C

\*Please inquire about the other Attenuator value

## Power Derating Curve

For resistors operated in ambient temperature above 70 °C, power rating shall be derated in accordance with the figure on the right.

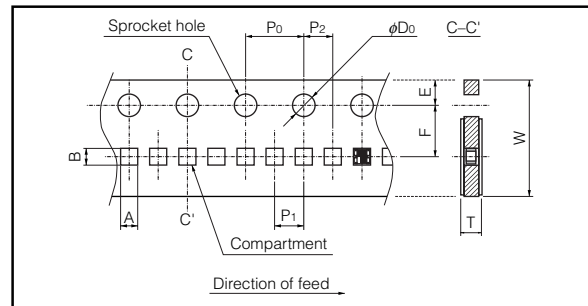


## ■ Packaging Methods (Taping)

### ● Standard Quantity

Type	Kind of Taping	Pitch (P <sub>1</sub> )	Quantity
EXB14AT EXB24AT	Punched Carrier Taping	2 mm	10000 pcs./reel

### ● Punched Carrier Taping

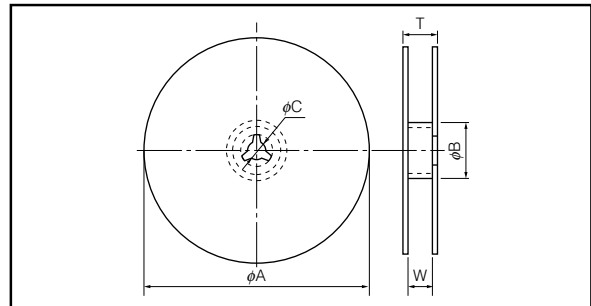


Dimensions (mm)	Type	A	B	W	F	E
	EXB14AT	0.70 <sup>+0.10</sup> <sub>-0.05</sub>	0.95 <sup>+0.05</sup> <sub>-0.10</sub>	8.00±0.20	3.50±0.05	1.75±0.10
EXB24AT	1.20±0.10	1.20±0.10				

Dimensions (mm)	Type	P <sub>0</sub>	P <sub>1</sub>	P <sub>2</sub>	φD <sub>0</sub>	T
	EXB14AT	4.00±0.10	2.00±0.10	2.00±0.05	1.50 <sup>+0.10</sup> <sub>-0</sub>	0.52±0.05
EXB24AT					0.45±0.10	

### ● Taping Reel



Dimensions (mm)	φA	φB	φC	W	T
		180.0 <sup>-0</sup> <sub>-3.0</sub>	60 min.	13.0 <sup>+1.0</sup>	9.0 <sup>+1.0</sup>

<Product direction in the chip pocket of carrier tape>  
Products shall be sealed as to locate the terminal 1 and 2 on the side of feeding direction in the chip pocket.

## ■ Recommended Land Pattern (mm)

□ Conductor

▨ Solder Resist

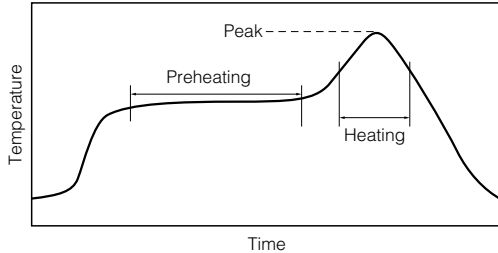
Type	Dimensions (mm)			
	a	b	c	d
EXB14AT	0.3	0.30	0.30	0.8 to 0.9
EXB24AT	0.5	0.35 to 0.40	0.3	1.4 to 1.5

Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use. Should a safety concern arise regarding this product, please be sure to contact us immediately.

■ **Recommended Soldering Conditions**

Recommendations and precautions are described below.

- Recommended soldering conditions for reflow
  - Reflow soldering shall be performed a maximum of two times.
  - Please contact us for additional information when used in conditions other than those specified.
  - Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example : Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example : Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

● **Flow soldering**

We do not recommend flow soldering, because solder bridging may occur due to the narrow 0.50 mm pitch(EXB14AT), 0.65 mm pitch(EXB24AT).

⚠ **Safety Precautions**

The following are precautions for individual products. Please also refer to the precautions common to Fixed Resistors shown on page ER3 of this catalog.

1. Take measures against mechanical stress during and after mounting of Chip Attenuator (hereafter called the resistors) so as not to damage their electrodes and protective coatings.  
Be careful not to misplace the resistors on the land patterns. Otherwise, solder bridging may occur.
2. If a transient load (heavy load in a short time) like a pulse is expected to be applied, check and evaluate the operations of the resistors when installed in your products before use.  
Never exceed the rated power. Otherwise, the performance and/or reliability of the resistors may be impaired.
3. Do not use halogen-based or other high-activity flux. Otherwise, the residue may impair the resistors' performance and/or reliability.
4. When soldering with a soldering iron, never touch the resistors' bodies with the tip of the soldering iron. When using a soldering iron with a high temperature tip, finish soldering as quickly as possible (within three seconds at 350 °C max.).
5. As the amount of applied solder becomes larger, the mechanical stress applied to the resistors increases, causing problems such as cracks and faulty characteristics. Avoid applying an excessive amounts of solder.
6. Do not apply shock to the resistors or pinch them with a hard tool (e.g. pliers and tweezers). Otherwise, the resistors' protective coatings and bodies may be chipped, affecting their performance.
7. Avoid excessive bending of printed circuit boards in order to protect the resistors from abnormal stress.

## ⚠ Safety Precautions (Common precautions for Fixed Resistors)

- When using our products, no matter what sort of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this catalog are subject to change without prior notice.
- Do not use the products beyond the specifications described in this catalog.
- This catalog explains the quality and performance of the products as individual components. Before use, check and evaluate their operations when installed in your products.
- Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other significant damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/gas equipment, rotating equipment, and disaster/crime prevention equipment.
- \* Systems equipped with a protection circuit and a protection device
- \* Systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault

### (1) Precautions for use

- These products are designed and manufactured for general and standard use in general electronic equipment (e.g. AV equipment, home electric appliances, office equipment, information and communication equipment)
- These products are not intended for use in the following special conditions. Before using the products, carefully check the effects on their quality and performance, and determine whether or not they can be used.
  1. In liquid, such as water, oil, chemicals, or organic solvent
  2. In direct sunlight, outdoors, or in dust
  3. In salty air or air with a high concentration of corrosive gas, such as Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, or NO<sub>2</sub>
  4. Electric Static Discharge (ESD) Environment  
These components are sensitive to static electricity and can be damaged under static shock (ESD). Please take measures to avoid any of these environments.  
Smaller components are more sensitive to ESD environment.
  5. Electromagnetic Environment  
Avoid any environment where strong electromagnetic waves exist.
  6. In an environment where these products cause dew condensation
  7. Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin or other materials
- These products generate Joule heat when energized. Carefully position these products so that their heat will not affect the other components.
- Carefully position these products so that their temperatures will not exceed the category temperature range due to the effects of neighboring heat-generating components. Do not mount or place heat-generating components or inflammables, such as vinyl-coated wires, near these products .
- Note that non-cleaning solder, halogen-based highly active flux, or water-soluble flux may deteriorate the performance or reliability of the products.
- Carefully select a flux cleaning agent for use after soldering. An unsuitable agent may deteriorate the performance or reliability. In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues. Otherwise, the insulation performance may be deteriorated.

### (2) Precautions for storage

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of 5 °C to 35 °C and a relative humidity of 45 % to 85 %.

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

1. In salty air or in air with a high concentration of corrosive gas, such as Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, or NO<sub>2</sub>
2. In direct sunlight

### <Package markings>

Package markings include the product number, quantity, and country of origin. In principle, the country of origin should be indicated in English.